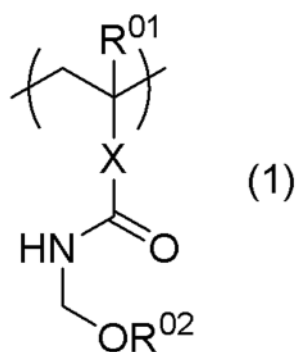


TITLE OF INVENTION: COMPOSITION FOR FORMING ADHESIVE
FILM, PATTERNING PROCESS, AND METHOD FOR FORMING
ADHESIVE FILM

ABSTRACT

The present invention is a composition for forming an adhesive film includes: (A) a resin containing a repeating unit represented by the following general formula (1) and a repeating unit having an organic sulfonyl anion structure; and (B) an organic solvent. The present invention provides: a composition for forming an adhesive film that exhibits favorable application performance even on a hydrophobic underlayer film and at the same time, yields an adhesive film having favorable pattern collapse prevention performance and ability to remove a residual resist at a bottom of a pattern; a patterning process using the composition; and a method for forming the adhesive film, in a fine patterning process of a multilayer resist method in a manufacturing process of a semiconductor apparatus.



[FIG. 1(A)-1(G)]